

QT-Brightek Side View LED Series

0602 Side View (Right Angle) LED

Part No.: QBLP617-Y5-2897

**2897: High Brightness Version
5: 5mA**



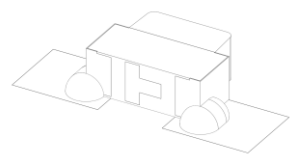
Table of Contents:

Introduction 3
Electrical / Optical Characteristic (Ta=25 °C) 4
Absolute Maximum Rating 4
Characteristic Curves..... 5
Solder Profile & Footprint 6
Mounting the LED on PCB 7
Packing 8
Labeling 9
Ordering Information 9
Revision History 10
Disclaimer 10

Introduction

Feature:

- Water clear lens
- Package in tape and reel
- Side view (right angle) 0602 LED package
- AllInGaP technology
- Beam Angle: 140° typ.
- Height profile: 0.6mm



Application:

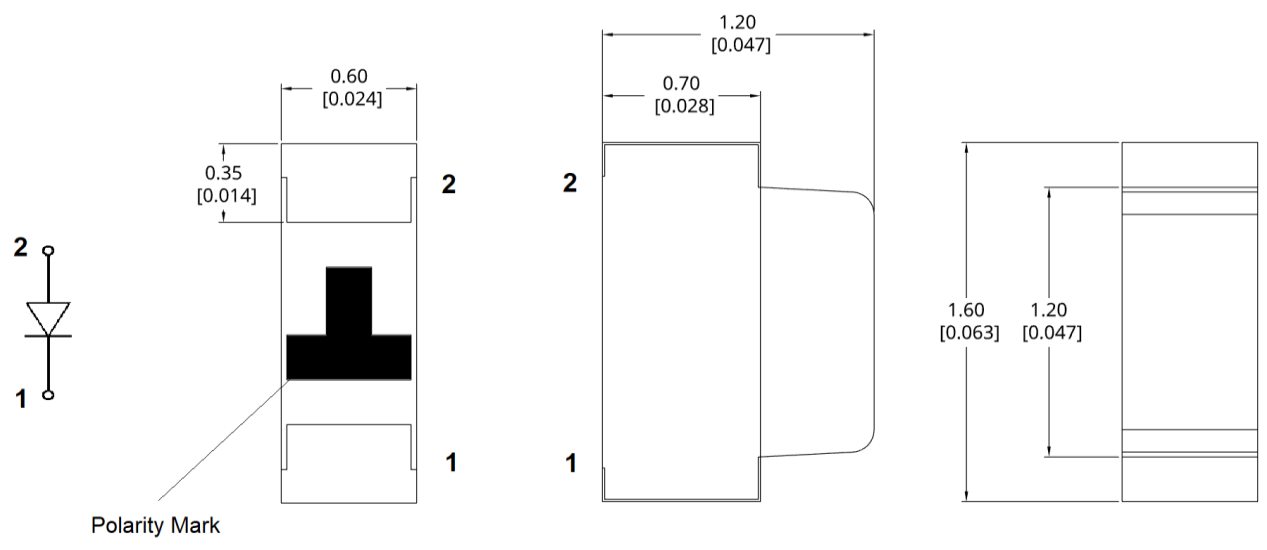
- Status indication
- Back lighting application
- General Use

Certification & Compliance:

- ISO9001
- RoHS Compliant



Dimension:



Units: mm / tolerance = +/-0.1mm



Electrical / Optical Characteristic (Ta=25 °C)

Product	Color	I _F (mA)	V _F (V)		λ _D (nm)			λ _P (nm)	I _V (mcd)		
			Typ.	Max.	Min.	Typ.	Max.	Typ.	Min.	Typ.	Max.
QBLP617-Y5-2897	Yellow	5	2.0	2.3	585	590	595	595	50	90	160

Absolute Maximum Rating

Material	P _d (mW)	I _F (mA)	I _{FP} (mA)*	V _R (V)	T _{OP} (°C)	T _{ST} (°C)	T _{SOI} (°C)**
AllnGaP	69	30	125	5	-40 to +80	-40 to +85	260

*Duty 1/8 @ 1kHz

**IR Reflow for no more than 10 sec @ 260 °C

Forward Voltage V_F @ I_F=5mA

Bin	Min.	Max.	Unit
□	1.7	2.3	V

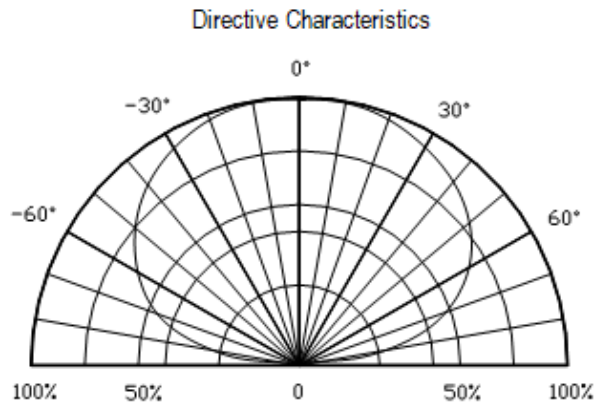
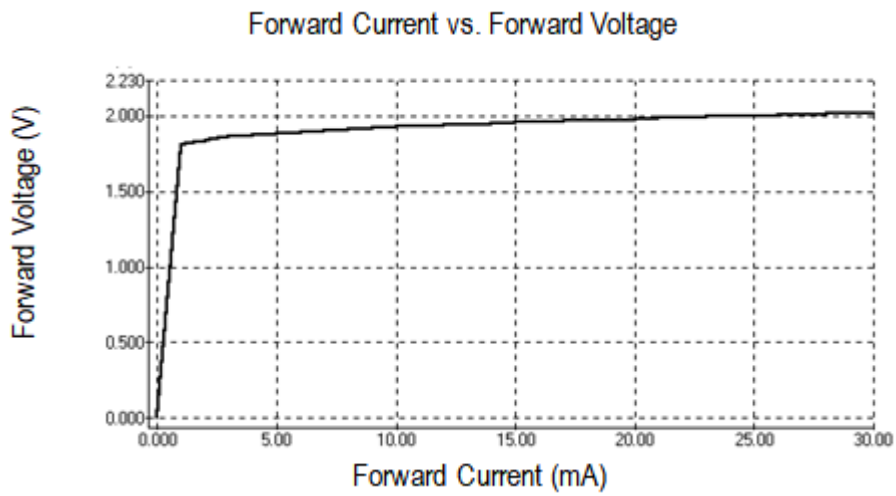
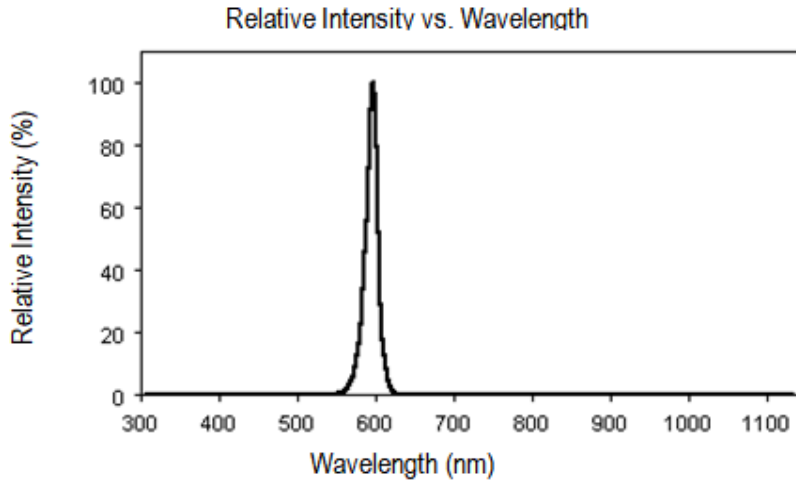
Luminous Intensity I_V @ I_F=5mA

Bin	Min.	Max.	Unit
G	50	63	mcd
H	63	80	
I	80	100	
J	100	125	
K	125	160	

Dominant Wavelength λ_D @ I_F=5mA

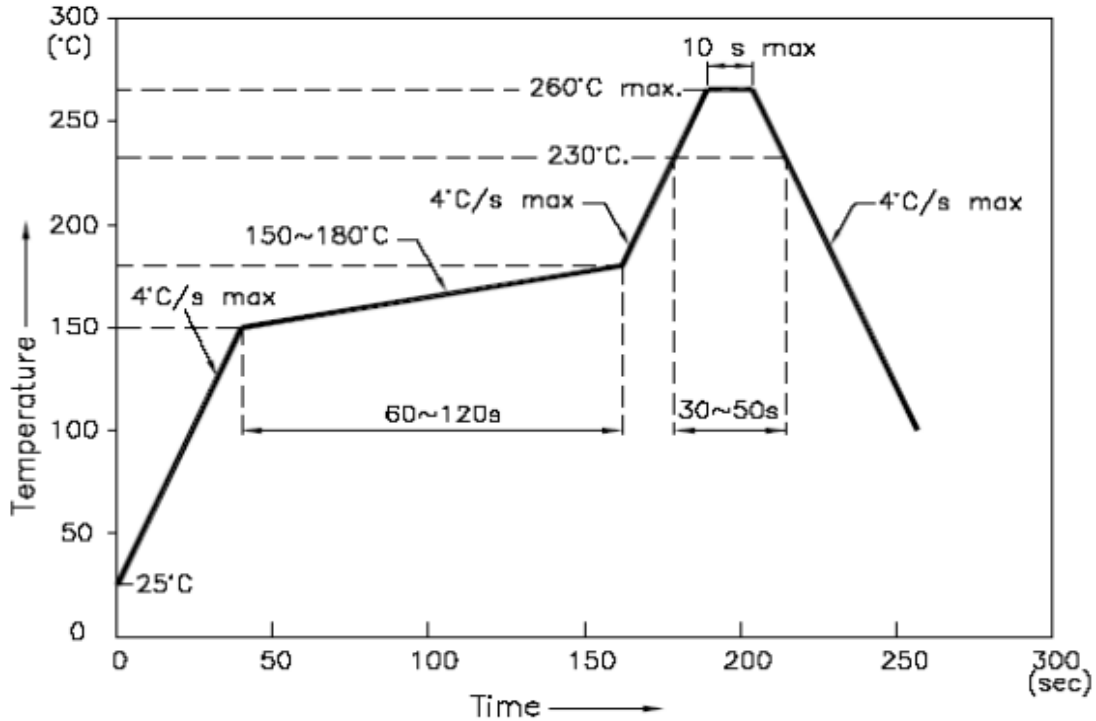
Bin	Min.	Max.	Unit
m	585	590	nm
n	590	595	

Characteristic Curves

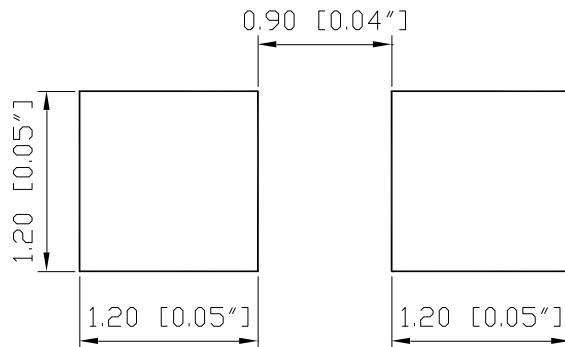


Solder Profile & Footprint

- Recommended tin solder specifications: melting temperature in the range of 178~192 °C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

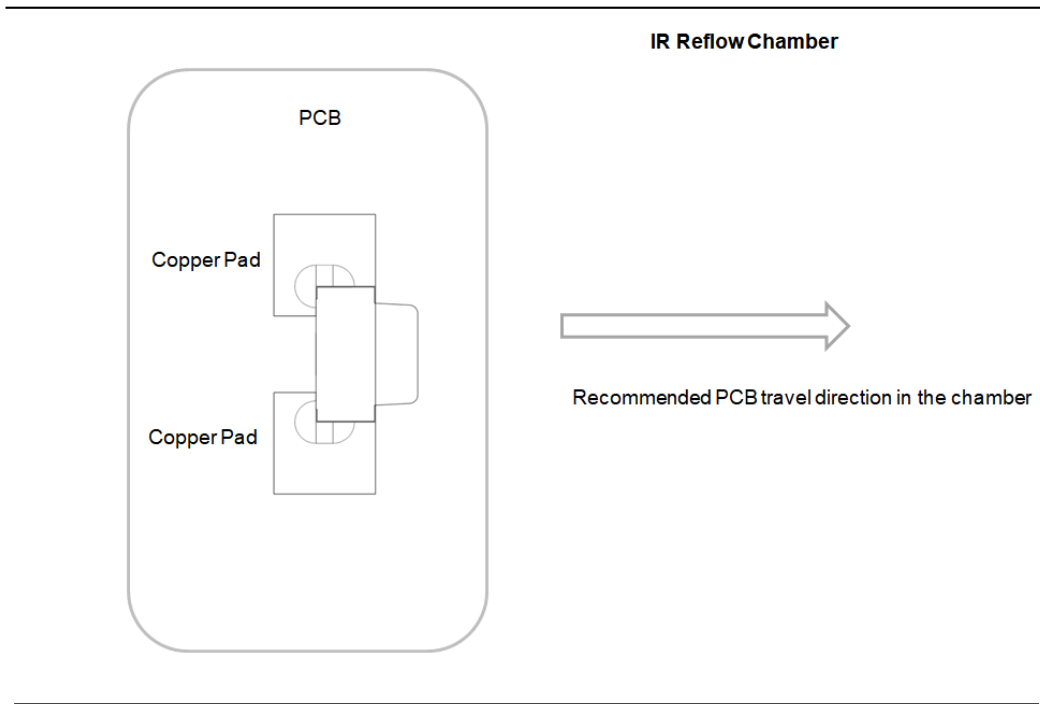


Recommended Pad Layout



Units: mm

- The recommended IR reflow direction for a right angle (side view) SMD led is illustrated below to insure the solder on each lead melts simultaneously during the SMT reflow soldering process.



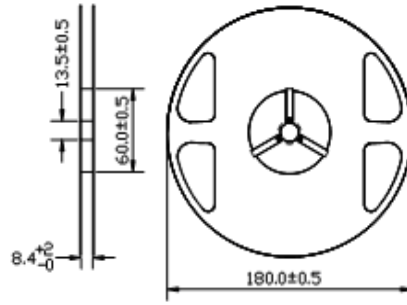
Mounting the LED on PCB



Note: The amount of solder paste applied as shown in the picture is just for illustration purpose only. When mounting and soldering the LEDs, avoid excess solder paste from overflowing onto or near the epoxy lens.

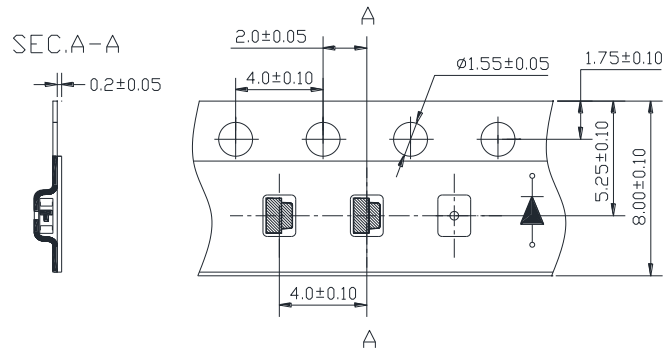
Packing

Reel Dimension:



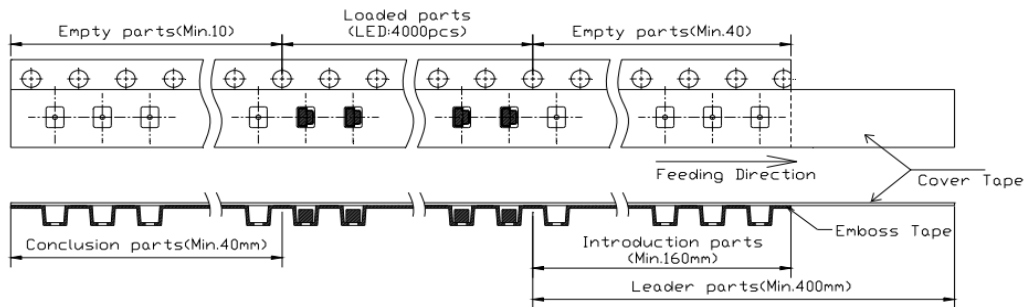
Unit: mm

Tape Dimension:

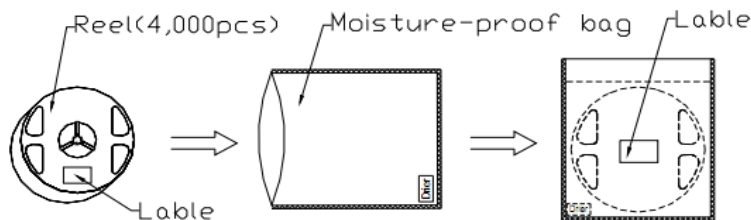


Unit: mm

Arrangement of Tape:



Packaging Specifications:



Labeling



Part No: _____
Customer P/N: _____
Item: _____
Q'ty: _____
Vf: _____
Iv: _____
WI: _____
Date: _____

Made in China

Ordering Information

Orderable Part #	Spec Range	Quantity per reel
QBLP617-Y5-2897	Iv=90mcd typ. @ 5mA / Color=585nm ~ 595nm	4,000 units



Revision History

Description:	Revision #	Revision Date
New Release of QBLP617-Y5-2897	V1.0	10/29/2024

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.